

Providing a quartz substrate having
Mosi thereon, preferably at a thickness which
corresponds to a 0 (or 360) degree phase shift
(i.e., coating a blank mask/resist onto
a substrate of MoSi and quartz,
writing and developing a pattern into
the MoSi, and etching the MoSi)

etching (i.e., where the MoSi pattern is not on the quartz substrate) a pattern into the quartz substrate at a depth which corresponds to a phase shift of 180 degrees

Resist strip and clean

Figure 2

